

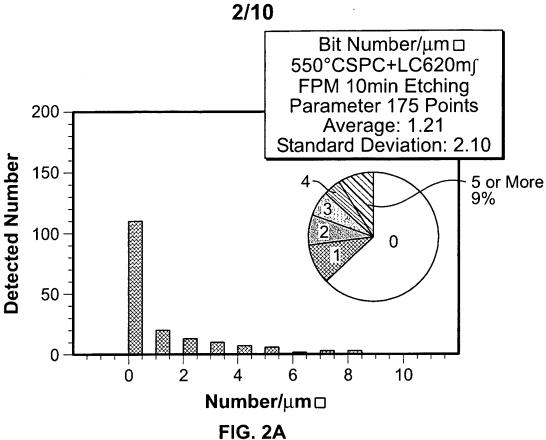
FIG. 1E

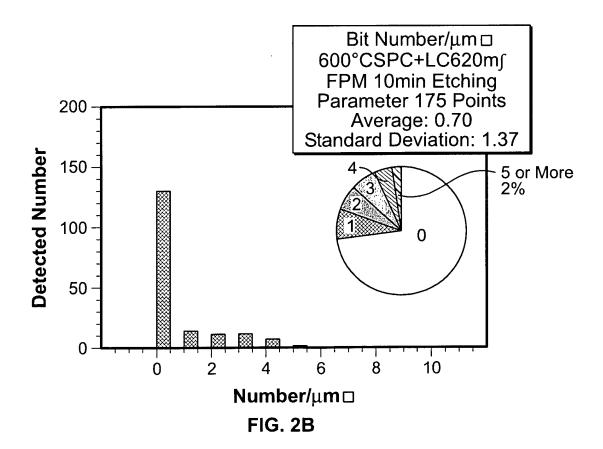


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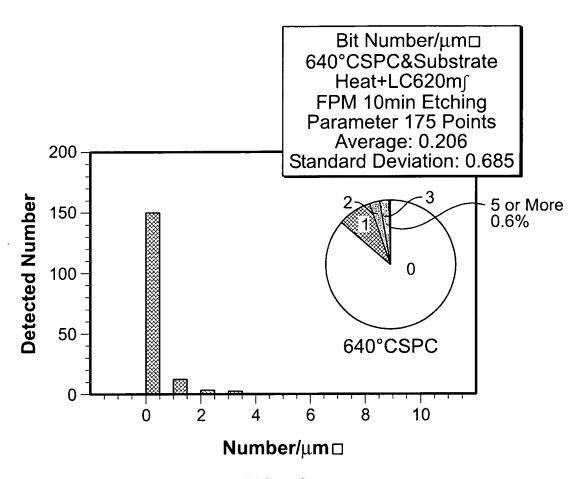


FIG. 2C



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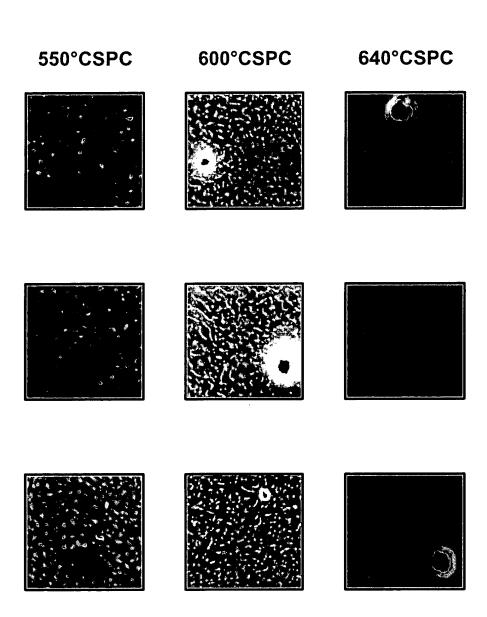
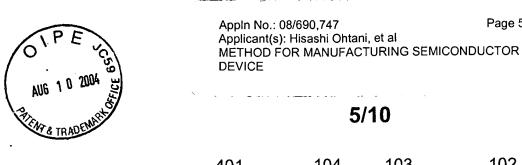
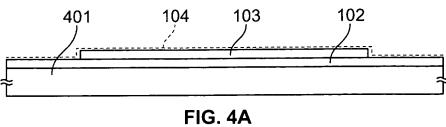
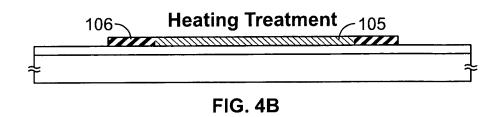


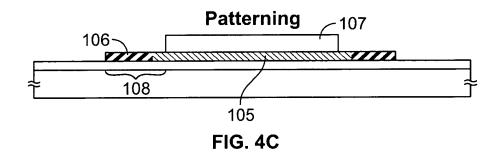
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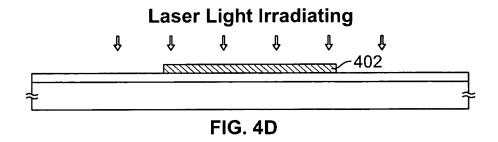


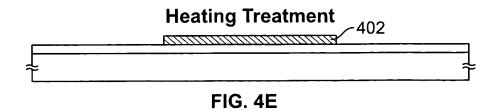


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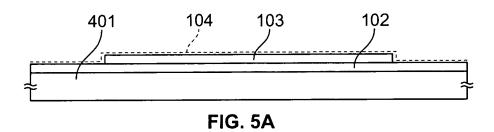


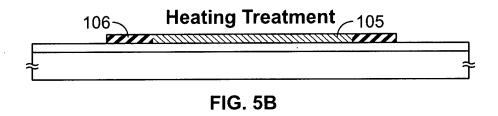


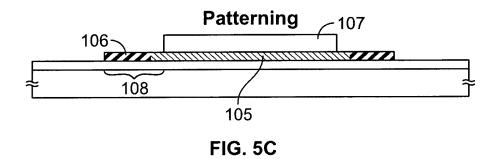
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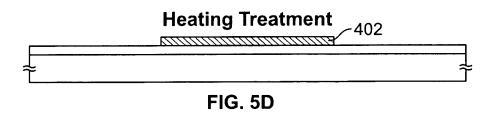
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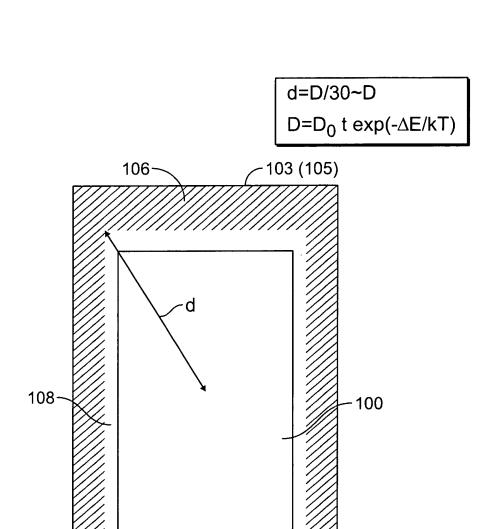


FIG. 6

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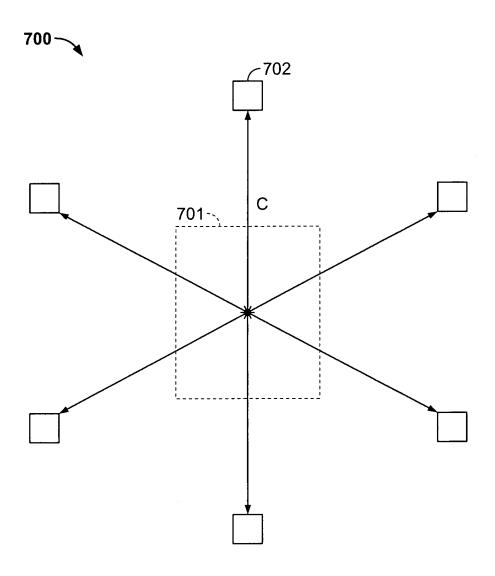
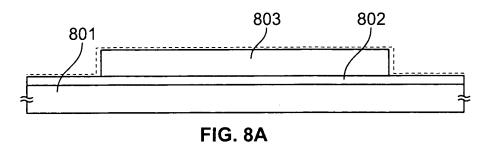
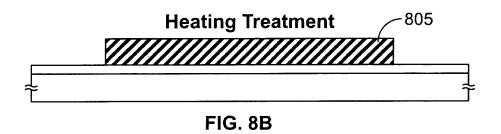


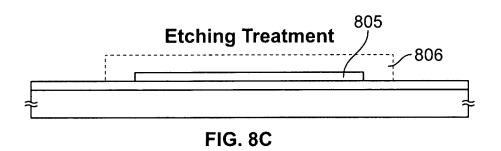
FIG. 7

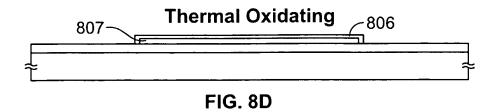


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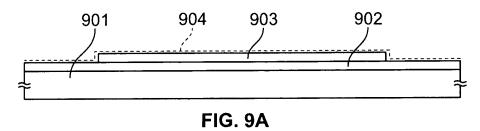


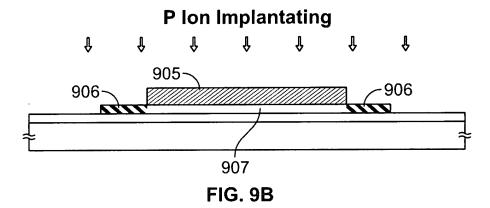


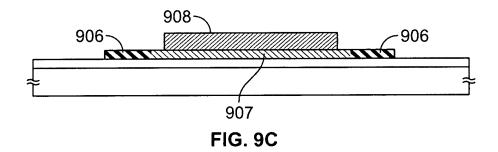




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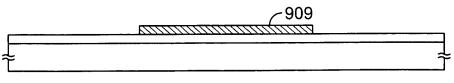


FIG. 9D